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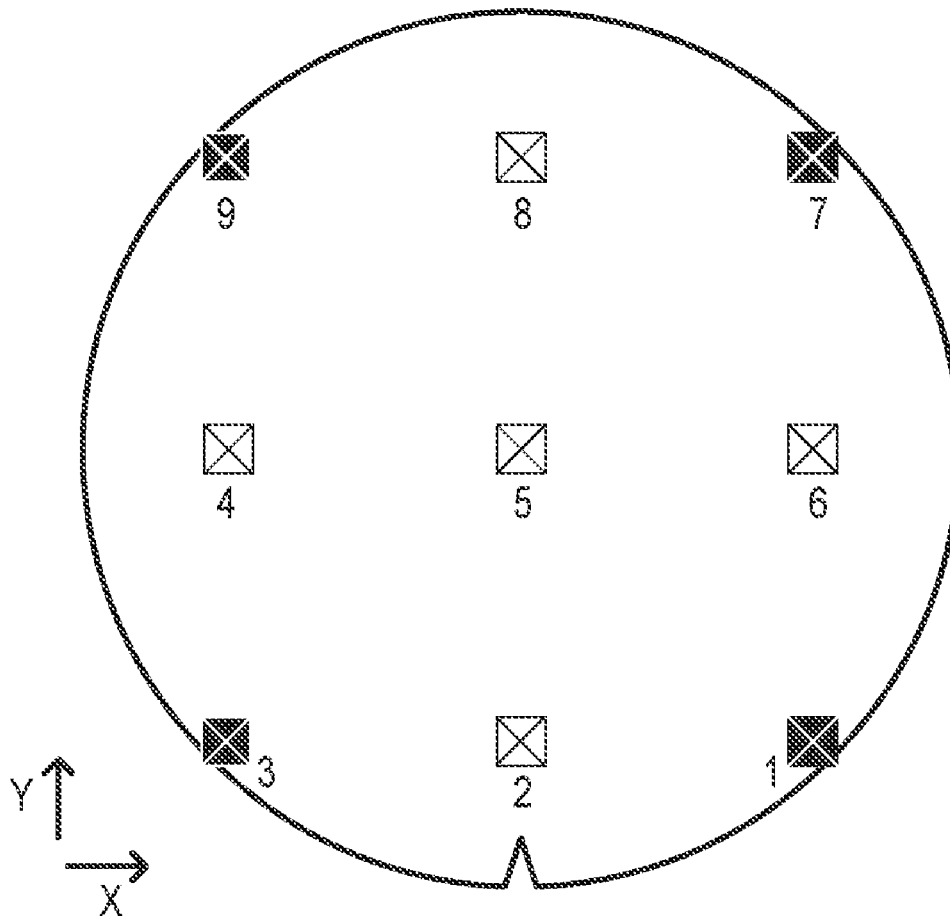
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(57) **ABSTRACT**

An acquisition method of acquiring identification information of a substrate from measurement results of a plurality of patterns formed on the substrate is provided. The method includes specifying the identification information based on first information extracted, in accordance with a first rule, from respective positions of regions where the plurality of patterns respectively exist and second information extracted from respective states of the plurality of patterns in accordance with a second rule.



MEASUREMENT MARK
(NORMAL VALUE)



MEASUREMENT MARK
(ABNORMAL VALUE)